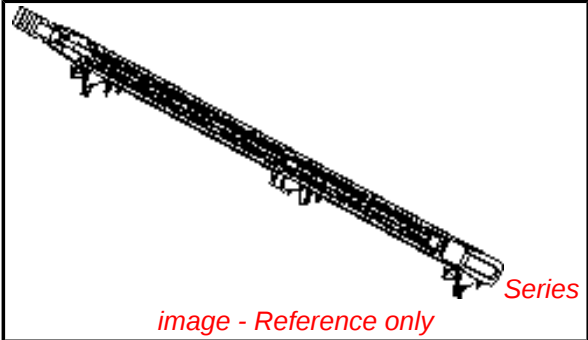


PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0878030002](#)
Status: **Active**
Description: 1.00mm (.039") Pitch DDR-2 DIMM Socket, 25 Degree Angle, Through Hole, 1.8V Voltage Key, 2.79mm (.110") Tail Length, 0.38µm (15µ") Gold (Au) Plating, 240 Circuits, Lead-free

Documents:
[3D Model](#)
[Drawing \(PDF\)](#)

[Product Specification PS-87803-003 \(PDF\)](#)
[RoHS Certificate of Compliance \(PDF\)](#)



Agency Certification

CSA LR19980
UL E29179

General

Product Family Memory Module Sockets
Series [87803](#)
Comments No Lubricant at the Contact|Latches in Off-White Color
Component Type Socket
JEDEC Outline MO-237
Product Name DDR2 DIMM

Physical

Circuits (Loaded) 240
Color - Resin Black, Natural
Durability (mating cycles max) 25
Entry Angle 25° Angle
Flammability 94V-0
Keying to Mating Part Yes
Material - Plating Mating Gold
Material - Plating Termination Tin
Material - Resin High Temperature Thermoplastic
PC Tail Length (in) 0.110 In
PC Tail Length (mm) 2.79 mm
PCB Locator Yes
PCB Retention Yes
PCB Thickness Recommended (in) 0.062 In
PCB Thickness Recommended (mm) 1.60 mm
Packaging Type Tray
Pitch - Mating Interface (in) 0.039 In
Pitch - Mating Interface (mm) 1.00 mm
Plating min: Mating (µin) 15
Plating min: Mating (µm) 0.38
Plating min: Termination (µin) 100
Plating min: Termination (µm) 2.54
Temperature Range - Operating -55°C to +85°C
Termination Interface: Style Through Hole

Electrical

Current - Maximum per Contact 0.5A
Voltage - Maximum 30V AC (RMS)/DC
Voltage Key 1.8V, Center

Solder Process Data

Duration at Max. Process Temperature (seconds) 5
Lead-free Process Capability SMC & Wave Capable (TH only)

EU RoHS
ELV and RoHS
Compliant
REACH SVHC
Contains SVHC: No
Halogen-Free
Status
Not Halogen-Free

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
[87803Series](#)

Mates With
JEDEC standard 1.27mm modules

Max. Cycles at Max. Process Temperature	2
Process Temperature max. C	260

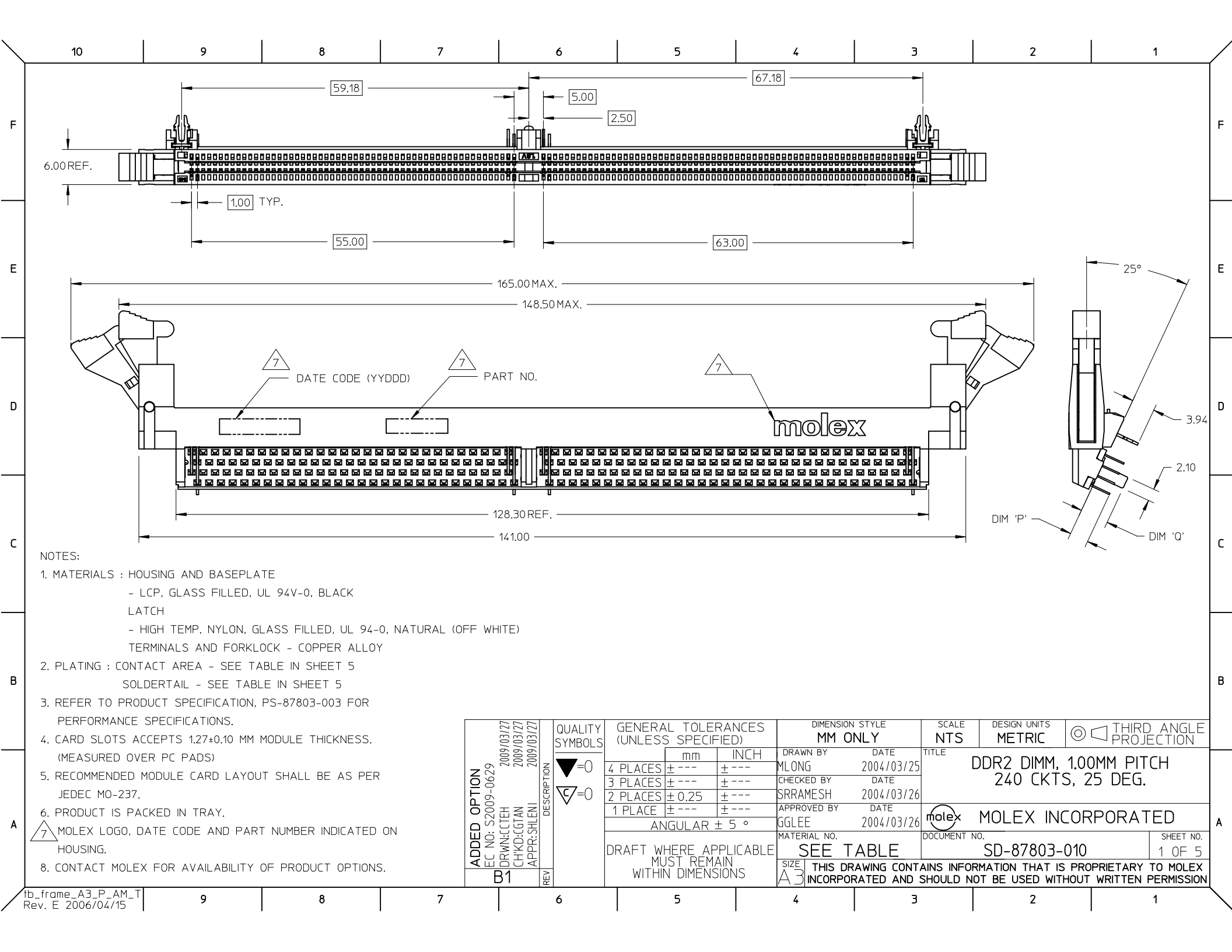
Material Info

Reference - Drawing Numbers

Product Specification	PS-87803-003
Sales Drawing	SD-87803-010

This document was generated on 04/09/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION



NOTES:

1. MATERIALS : HOUSING AND BASEPLATE
- LCP, GLASS FILLED, UL 94V-0, BLACK
LATCH
- HIGH TEMP. NYLON, GLASS FILLED, UL 94-0, NATURAL (OFF WHITE)
TERMINALS AND FORKLOCK - COPPER ALLOY
2. PLATING : CONTACT AREA - SEE TABLE IN SHEET 5
SOLDERTAIL - SEE TABLE IN SHEET 5
3. REFER TO PRODUCT SPECIFICATION, PS-87803-003 FOR PERFORMANCE SPECIFICATIONS.
4. CARD SLOTS ACCEPTS 1.27±0.10 MM MODULE THICKNESS. (MEASURED OVER PC PADS)
5. RECOMMENDED MODULE CARD LAYOUT SHALL BE AS PER JEDEC MO-237.
6. PRODUCT IS PACKED IN TRAY.
7. MOLEX LOGO, DATE CODE AND PART NUMBER INDICATED ON HOUSING.
8. CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.

ADDED OPTION EC NO: S2009-0629 2009/03/27 DRWN:CCTEH CHKD:CGTAN 2009/03/27 APPR:SHLENI 2009/03/27	DESCRIPTION	QUALITY SYMBOLS ▽=0 ◻=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG. MOLEX MOLEX INCORPORATED DOCUMENT NO. SD-87803-010 SHEET NO. 1 OF 5
					DRAWN BY MLONG	DATE 2004/03/25	TITLE		
					CHECKED BY SRAMESH	DATE 2004/03/26			
					APPROVED BY GGLEE	DATE 2004/03/26			
					MATERIAL NO.				
					SEE TABLE				
					SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				

10 9 8 7 6 5 4 3 2 1

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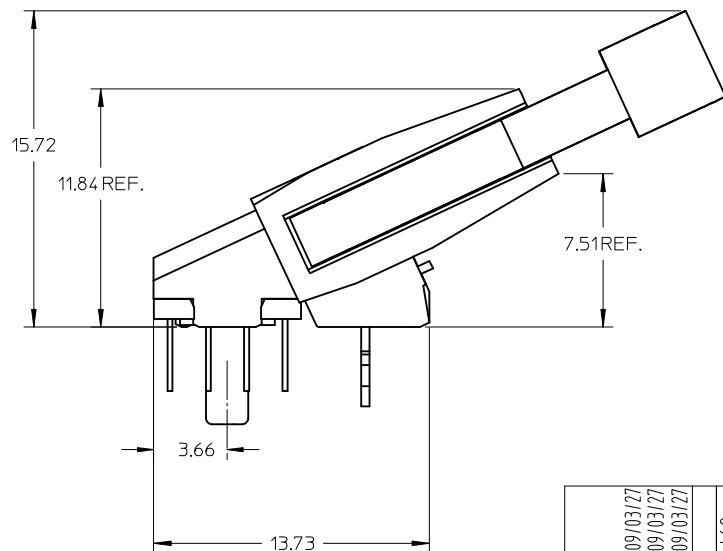
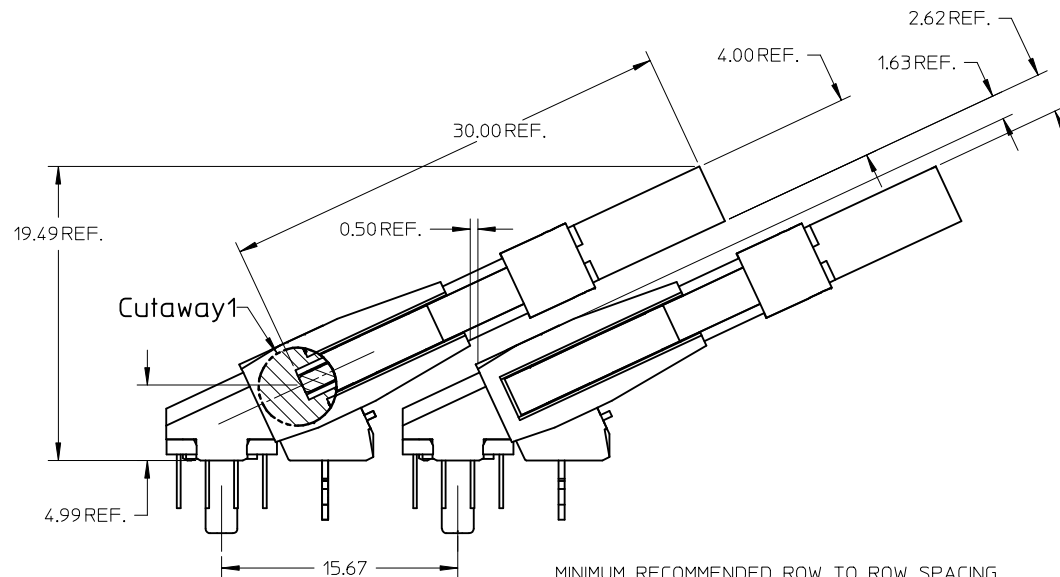
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C

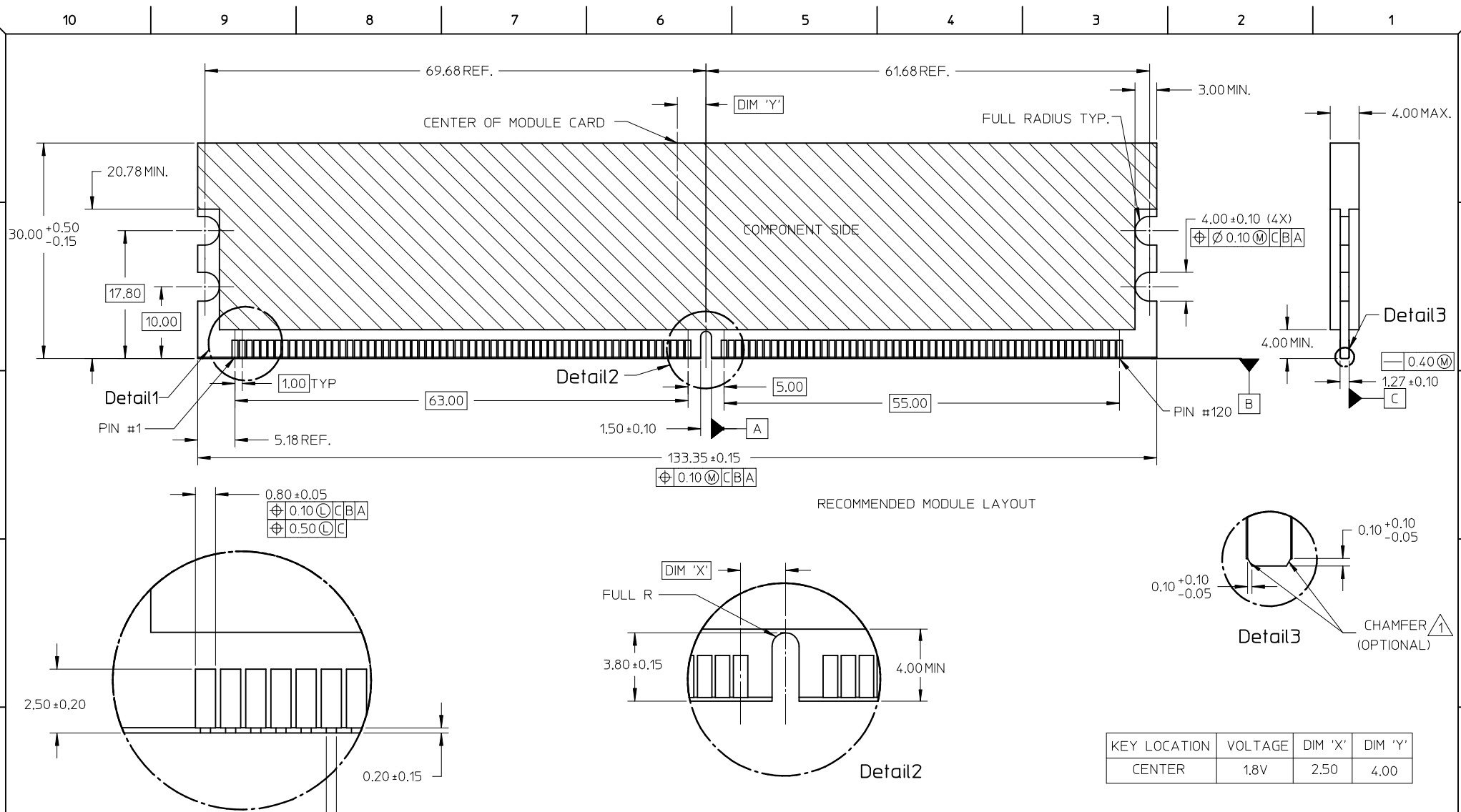
B

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ADDED OPTION EC NO: S2009-0629 DRWN: CCTEH CHKD: CGTAN APPR: SHLENI	2009/03/27 2009/03/27 2009/03/27 2009/03/27	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
					mm	INCH	DRAWN BY	DATE	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.		
				4 PLACES	± ---	± ---	MLONG	2004/03/25			
				3 PLACES	± ---	± ---	CHECKED BY	DATE			
				2 PLACES	± 0.25	± ---	SRRAMESH	2004/03/26			
				1 PLACE	± ---	± ---	APPROVED BY	DATE	MOLEX INCORPORATED		
				ANGULAR ± 5 °		GGLEE	2004/03/26				
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		SHEET NO.	
						SEE TABLE		SD-87803-010		2 OF 5	
B1		REV				SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

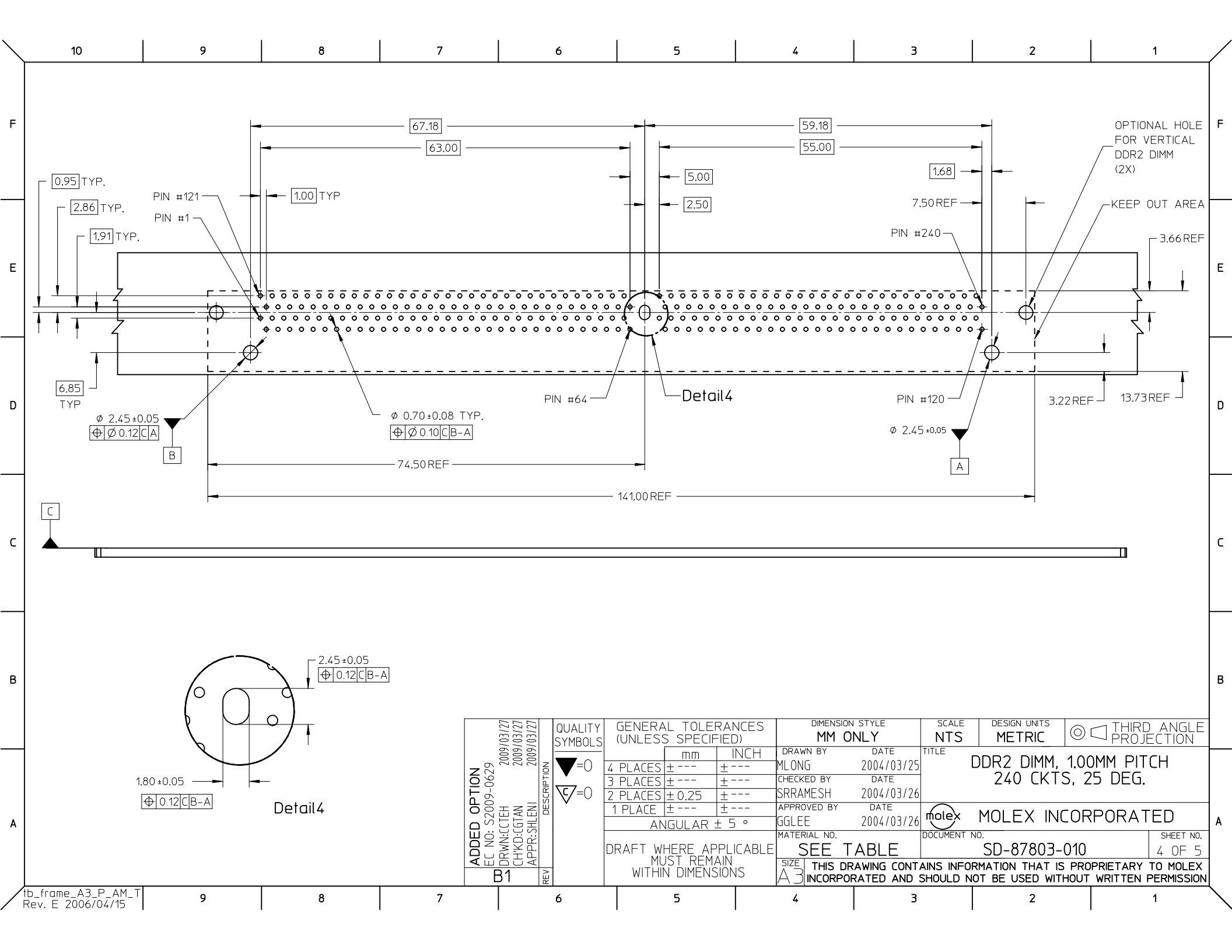
9 8 7 6 5 4 3 2 1



KEY LOCATION	VOLTAGE	DIM 'X'	DIM 'Y'
CENTER	1.8V	2.50	4.00

NOTES:
 1. MODULE CARD USED IN PRODUCT TESTING ARE CHAMFERED.

ADDED OPTION EC NO: S2009-0629 DRWN:CTEH CHKD:CGTAN APPR:SHLENI 2009/03/27 2009/03/27 2009/03/27	DESCRIPTION REV	QUALITY SYMBOLS ▽=0 □=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION ⊙ □				
				mm	INCH	DRAWN BY MLONG	DATE 2004/03/25	TITLE DDR2 DIMM, 1.00MM PITCH 240 CKTS, 25 DEG.					
			4 PLACES	± ---	± ---	CHECKED BY SRRAMESH	DATE 2004/03/26						
			3 PLACES	± ---	± ---	APPROVED BY GGLEE		DATE 2004/03/26	MOLEX INCORPORATED				
			2 PLACES	± 0.25	± ---								
			1 PLACE	± ---	± ---	MATERIAL NO.		DOCUMENT NO. SD-87803-010					
			ANGULAR ± 5 °										
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE TABLE		SHEET NO. 3 OF 5					
						SIZE A3							
						THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION							



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PART NO.	VOLTAGE KEY	DIM 'P'	DIM 'Q'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING	SOLDERTAIL PLATING	LUBRICATION			
87803-0002	1.8V	2.79	3.18	1.57	0.38µM/ 15µ" GOLD OVER 1.27µM/ 50µ" MIN NICKEL	2.54µM/ 100µ" MIN. TIN (MATTE) OVER 1.27µM/ 50µ" MIN NICKEL	NO			
87803-0022							YES			
87803-0012		3.18	4.83	2.36			NO			
87803-0032							YES			
87803-0052		4.00		3.18			NO			
87803-0062							YES			
87803-0102		2.79	3.18	1.57	0.76µM/ 30µ" GOLD OVER 1.27µM/ 50µ" MIN NICKEL		NO			
87803-0122							YES			
87803-0112		3.18	4.83	2.36			NO			
87803-0132							YES			
87803-0152		4.00		3.18			NO			
87803-0162							YES			

ADDED OPTION

EC NO: S2009-0629

DRWN: CTEH

CHKD: GTAN

APPR: SILENI

REV

B1

2009/03/27

2009/03/27

2009/03/27

DESCRIPTION

QUALITY SYMBOLS

▽=0

◻=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.25	± ---
1 PLACE	± ---	± ---

ANGULAR ± 5 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE

MM ONLY

DRAWN BY	DATE
MLONG	2004/03/25
CHECKED BY	DATE
SRRAMESH	2004/03/26
APPROVED BY	DATE
GGLEE	2004/03/26

MATERIAL NO.

SEE TABLE

SIZE

A3

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SCALE

NTS

DESIGN UNITS

METRIC

THIRD ANGLE PROJECTION

TITLE

DDR2 DIMM, 1.00MM PITCH
240 CKTS, 25 DEG.

MOLEX

MOLEX INCORPORATED

DOCUMENT NO.

SD-87803-010

SHEET NO.

5 OF 5